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General Information

类别	SMD Comm C0G
样式	SMD Chip
描述	SMD, MLCC, Ultra-Stable, Low Loss, Class I
特征	Ultra-Stable, Low Loss, Class I
RoHS	Yes
端子	Tin
标记	No
AEC-Q200	No
典型元件重量	25 mg
保质期	78 Weeks
MSL	1

Dimensions

L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.1mm +/-0.10mm
S	1.5mm MIN
B	0.5mm +/-0.25mm
Chip Size / Footprint	1206 / 3216

Packaging Specifications

包装	T&R, 180mm, Plastic Tape
包装数量	2500

Specifications

容值	2,200 pF
测量条件	1 kHz 1.0Vrms
容差	5%
直流电压	200 VDC
耐压电压	500 VDC
温度范围	-55/+125°C
温度系数	C0G
电容变化 (相对于+25°C, 0 VDC) (TCC)	30 ppm/C, 1kHz 1.0Vrms
损耗因数	0.1% 1 kHz 1.0Vrms
老化率	0% Loss/Decade Hour
绝缘阻抗	100 GOhms

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